

國立清華大學電機資訊學院

114學年度國際半導體暨IC設計產業人才專班申請表

College of Electrical Engineering and Computer Science
National Tsing Hua University

Application Form for International Semiconductor and IC Design Program 2025

I. Personal Information 申請人資料

Applicant No. 申請件編號 : (office use only)

Photo

照片

English Name 英文姓名 (as in passport)

Family Name:

Given Name:

Chinese Name 中文姓名 (optional)

Contact Email 電郵帳號

Date of Birth 生日 (year/month/date)

Country of Birth 出生地

Nationality 國籍

Passport Number 護照號碼 (If applicable)

Biological Gender 性別 : M(男) F(女)

Contact Information 聯絡資料

Address 戶籍地址

Street 街道:

City 城市:

Country 國家:

Zip code 郵遞區號:

E-mail 電子信箱:

Contact Phone/Mobile Phone 電話: (country code)+(phone number)

Emergency contact 緊急聯絡人

Name 姓名:

Relationship 關係:

Phone 電話:

Email 電子信箱:

Address 地址:

II. Education Background 教育背景

Highest Degree Received

Name of Institution 學校名稱:

Major in 系所:

School Address 學校地址

Street:

City:

State/ Province:

Postal/ Zip Code:

Country:

Date of Graduation 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____

Others

School Name 學校名稱:

Department or Focused Area 系所或專業領域:

School Address 學校地址

Street:

City:

State/ Province:

Postal/ Zip Code:

Country:

Date of Graduation 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____

Others

School Name 學校名稱:

Department or Focused Area 系所或專業領域:

School Address 學校地址

Street:

City:

State/ Province:

Postal/ Zip Code:

Country:

Date Graduated 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____

III. Mentionable Activity 亮點活動

You may list your mentionable achievements, work experience (if any), and other relevant experiences.

IV. Other Information 其他資訊

Financial Plan 在清華大學就學期間經濟來源

- Personal savings (個人存款)
- Other, please specify (其他，說明)
- Scholarships, please specify (獎學金，說明)

Language Proficiency 語言能力

English 英文

Fluent 傑出 Good 優秀 Moderate 好 Limited 普通 None 差

Mandarin 中文

Fluent 傑出 Good 優秀 Moderate 好 Limited 普通 None 差

Other, please specify 其他語言:

Fluent 傑出 Good 優秀 Moderate 好 Limited 普通 None 差

Accommodation 住宿申請

If available, are you interested in applying on-campus housing? 請問是否需要申請住宿

Yes No

V. Contacts for Recommendation Letters

Referee 推薦人 1

Name 姓名:

Current Position/Job Title 現職名稱:

Current Employer 現職單位:

E-mail 電子郵件:

Relationship with the applicant

與申請人之關係:

Referee 推薦人 2

Name 姓名:

Current Position/Job Title 現職名稱:

Current Employer 現職單位:

E-mail 電子郵件:

Relationship with the applicant

與申請人之關係:

VI. Statement of Purpose 學習計畫

Do you have preferred host professors 希望的指導教授？ Yes No

Have already contacted him/her 您是否已經與這位教授連繫？ Yes No

Professor's Name 教授姓名:

Department/Institute 系別:

E-mail 電子郵件:

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Application Checking List

Application Number: (office use only)

Applicant:

Nationality:

NOTE Please have the outgoing exchange program coordinator at your home institution to check your required documents and complete the following session I and II.

Section I		List of General Required Documents	
Application Package	<input type="checkbox"/>	Application Form with Statement of Purpose	
	<input type="checkbox"/>	An official copy of the Transcript (English)	
	<input type="checkbox"/>	A copy of your highest Degree Diploma	
	<input type="checkbox"/>	Recommendation Letters (Referees' Contacts)	
	<input type="checkbox"/>	Language Certificate <input type="checkbox"/> English Proficiency Test <input type="checkbox"/> Chinese Proficiency Test	
	<input type="checkbox"/>	A Copy of Passport Identity page (valid for at least 3 months) or nationality verification	
	<input type="checkbox"/>	Financial Certificate	
	<input type="checkbox"/>	Declaration Form	
	Section II		
Applicant's Statement	Certification		
	I certify that the information I have provided in this application is complete and correct. I understand that any misrepresentation, omission, or submission of false information is grounds for rejection of my application, withdrawal of acceptance, cancellation of enrollment, and/or disciplinary action at a future date. If my application is accepted, I agree to abide by the policies, rules, and regulations of the Republic of China and National Tsing Hua University.		
	Applicant's Signature (簽名) : _____		
	Date:		